

Dual N-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω) MAX.	I _D (A)	Q _g (TYP.)		
30	0.540 at V _{GS} = 4.5 V	0.5			
	0.600 at V _{GS} = 2.5 V	0.2	0.72 nC		
	0.700 at V _{GS} = 1.8 V	0.2	0.72110		
	1.100 at V _{GS} = 1.5 V	0.05			

SC-89 Dual (6 leads) S₂ G₂ 4 D₁ 5 Top View

Marking Code: B Ordering Information:

Si1036X-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

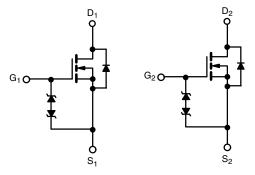
- TrenchFET® Power MOSFET
- 100 % R_a tested
- Gate-source ESD protected: 1000 V
- Material categorization:
 For definitions of compliance please see www.vishay.com/doc?99912



ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- Load switch
- · High speed switching
- DC/DC converters / boost converters
- · For smart phones, tablet PCs and mobile computing



N-Channel MOSFET

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V _{DS}	30	V	
Gate-Source Voltage		V_{GS}	± 8		
Continuous Dunis Comment (T. 150 °C) 2	T _A = 25 °C		0.61 ^{a,b}		
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 70 °C	l _D	0.49 ^{a,b}	Α	
Pulsed Drain Current (t = 100 μs)		I _{DM}	2		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	0.18 ^{a,b}	Α	
Maximum Dawar Dissipation 8	T _A = 25 °C	D	0.22 ^{a,b}	_ w	
Maximum Power Dissipation ^a	T _A = 70 °C	P _D	0.14 ^{a,b}		
Operating Junction and Storage Temperature Ra	ange	T _J , T _{stg}	-55 to 150	°C	

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient ^b	t ≤ 5 s	R _{thJA}	470	565	°C/W	
Waximum Junction-to-Ambient ~	Steady State		560	675		

Notes

a. Surface mounted on 1" x 1" FR4 board.

b. t = 5 s.



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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static				•		I.	
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30	-	-	V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	1 050 A	-	29	-	mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	-	-1.8	-	mv/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.4	-	1	V	
Cata Sauraa Laakaga		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$	-	-	± 30	μΑ	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$	-	-	± 1		
Zero Gate Voltage Drain Current	l	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$	-	-	3		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	2	-	-	Α	
		$V_{GS} = 4.5 \text{ V}, I_D = 0.5 \text{ A}$	-	0.450	0.540	- Ω	
Dunin Course On Chata Basistana 3	D	$V_{GS} = 2.5 \text{ V}, I_D = 0.2 \text{ A}$	-	0.500	0.600		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 1.8 \text{ V}, I_D = 0.2 \text{ A}$	-	0.560	0.700		
		$V_{GS} = 1.5 \text{ V}, I_D = 0.05 \text{ A}$	-	0.647	1.100		
Forward Transconductance	9 _{fs}	$V_{DS} = 15 \text{ V}, I_D = 0.5 \text{ A}$	-	7.5	-	S	
Dynamic ^b							
Input Capacitance	C _{iss}		-	36	-		
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	9	-	pF	
Reverse Transfer Capacitance	C _{rss}		-	5	-		
Total Cata Charge	0	$V_{DS} = 15 \text{ V}, V_{GS} = 8 \text{ V}, I_D = 0.5 \text{ A}$	-	1.2	2	nC	
Total Gate Charge	Q_g		-	0.72	1.2		
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 0.5 \text{ A}$	-	0.1	-		
Gate-Drain Charge	Q _{gd}		-	0.16	-	1	
Gate Resistance	R _g	f = 1 MHz	2.4	12.2	24.4	Ω	
Turn-On Delay Time	t _{d(on)}		-	6	15		
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_{L} = 37.5 \Omega$	-	13	24	ns	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 0.4 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$	-	20	30		
Fall Time	t _f		-	11	20		
Drain-Source Body Diode Characterist	ics						
Pulse Diode Forward Current ^a	I _{SM}		-	-	2	Α	
Body Diode Voltage	V _{SD}	I _S = 0.5 A	-	0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}		-	8	15	ns	
Body Diode Reverse Recovery Charge Q.,		1 044 41/44 400 47	-	2	4	nC	
Reverse Recovery Fall Time	t _a	t_a $t_F = 0.4 \text{ A, di/dt} = 100 \text{ A/}\mu\text{s}$		4	-	ns	
Reverse Recovery Rise Time	t _b			4	-		

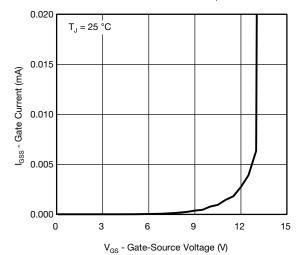
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

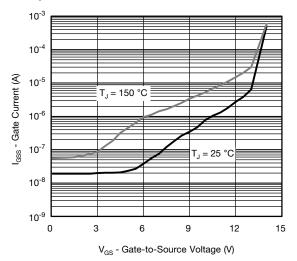
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



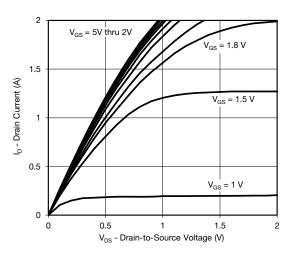
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



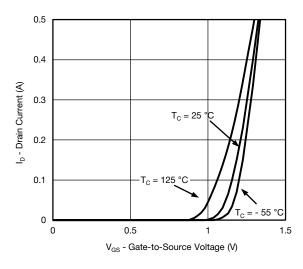
Gate Current vs. Gate-Source Voltage



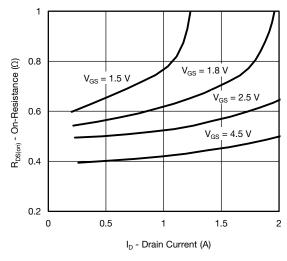
Gate Current vs. Gate-Source Voltage

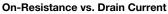


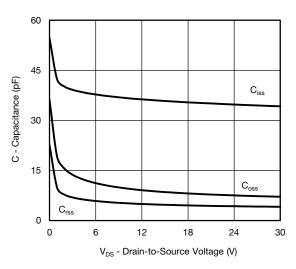
Output Characteristics



Transfer Characteristics



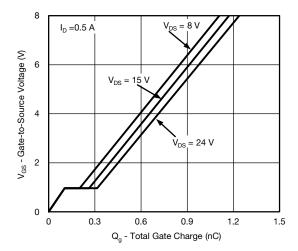




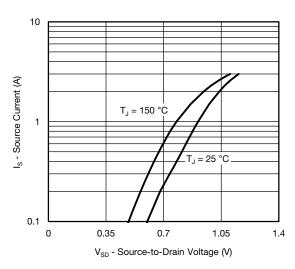
Capacitance



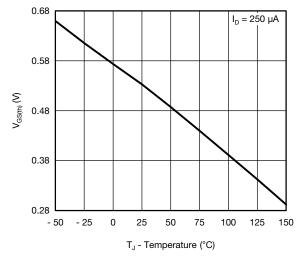
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



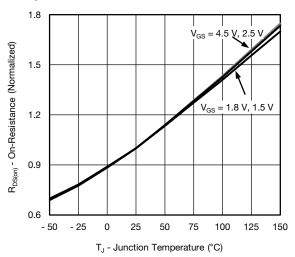
Gate Charge



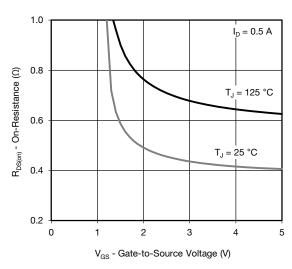
Soure-Drain Diode Forward Voltage



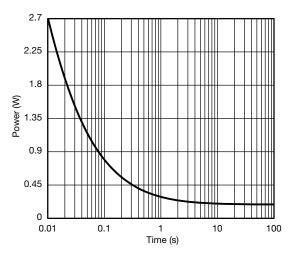
Threshold Voltage



On-Resistance vs. Junction Temperature



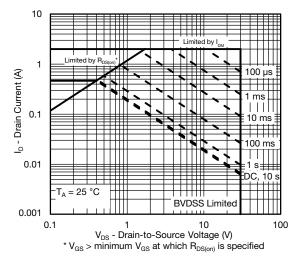
On-Resistance vs. Gate-to-Source Voltage

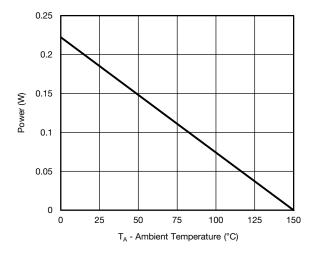


Single Pulse Power, Junction-to-Ambient



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

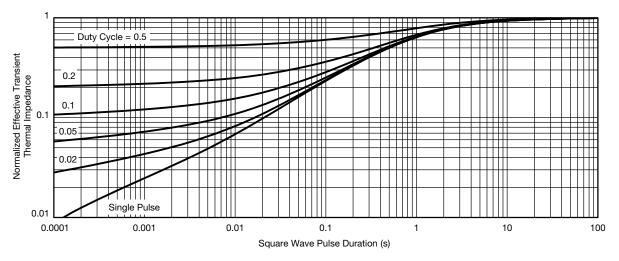




Safe Operating Area, Junction-to-Ambient

Power Derating, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max.)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

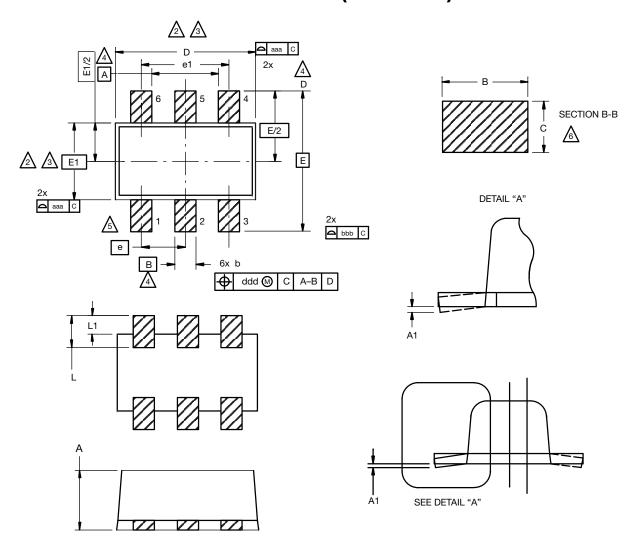


Normalized Thermal Transient Impedance, Junction-to-Ambient

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg262932.



SC-89 6-Leads (SOT-563F)



Notes

1. Dimensions in millimeters.

Dimension D does not include mold flash, protrusions or gate burrs. Mold flush, protrusions or gate burrs shall not exceed 0.15 mm per dimension E1 does not include interlead flash or protrusion, interlead flash or protrusion shall not exceed 0.15 mm per side.

Dimensions D and E1 are determined at the outmost extremes of the plastic body exclusive of mold flash, the bar burrs, gate burrs and interlead flash, but including any mismatch between the top and the bottom of the plastic body.

ADatums A, B and D to be determined 0.10 mm from the lead tip.

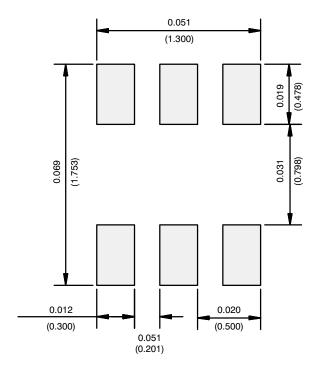
A Terminal numbers are shown for reference only.

These dimensions apply to the flat section of the lead between 0.08 mm and 0.15 mm from the lead tip.

DIM.	MILLIMETERS					
DIW.	MIN.	NOM.	MAX.			
Α	0.56	0.58	0.60			
A1	0	0.02	0.10			
b	0.15	0.22	0.30			
С	0.10	0.14	0.18			
D	1.50	1.60	1.70			
E	1.50	1.60	1.70			
E1	1.15	1.20	1.25			
е	0.45	0.50	0.55			
e1	0.95	1.00	1.05			
L	0.25	0.35	0.50			
L1	0.10	0.20	0.30			
C14-0439-Rev. C, 11-Aug-14 DWG: 5880						



RECOMMENDED MINIMUM PADS FOR SC-89: 6-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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